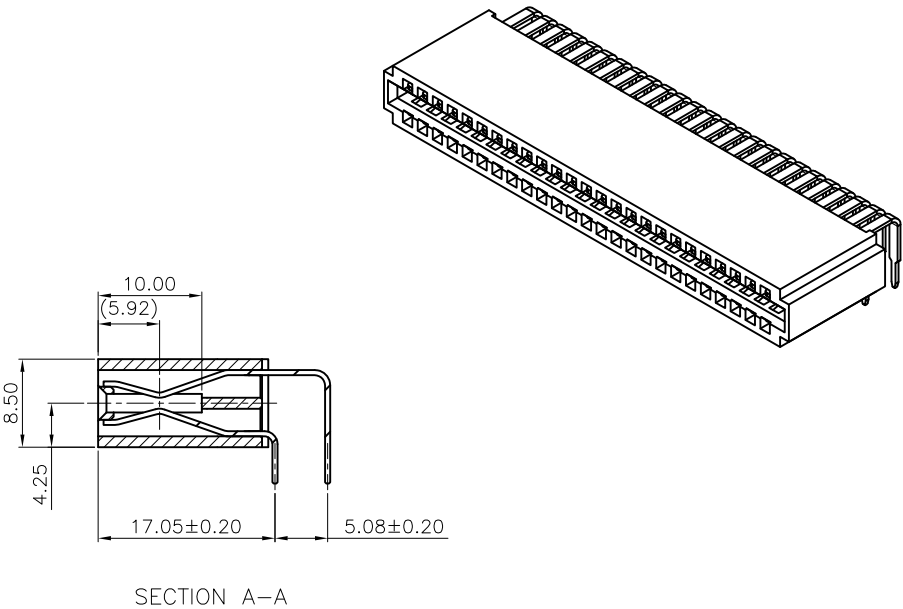
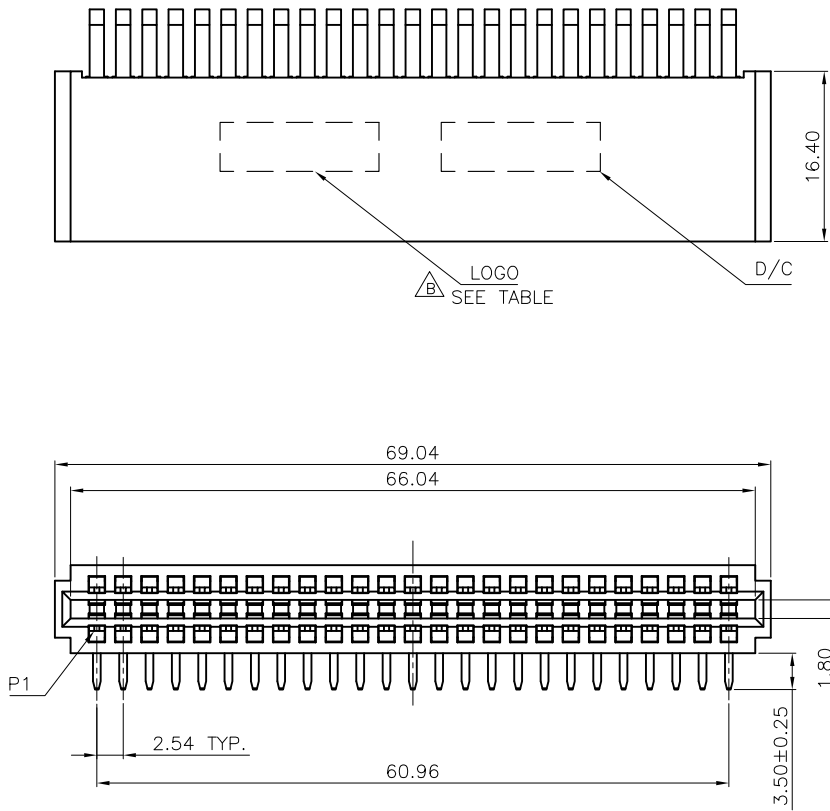
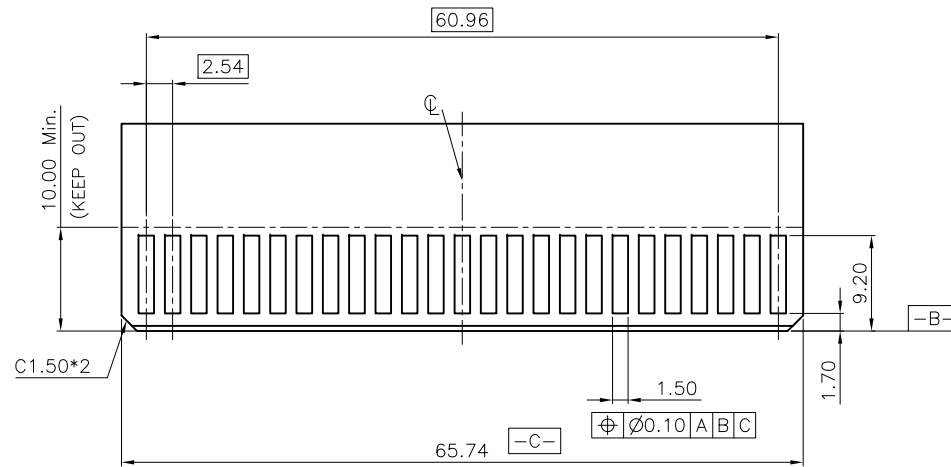


CONNECTOR NOTES:

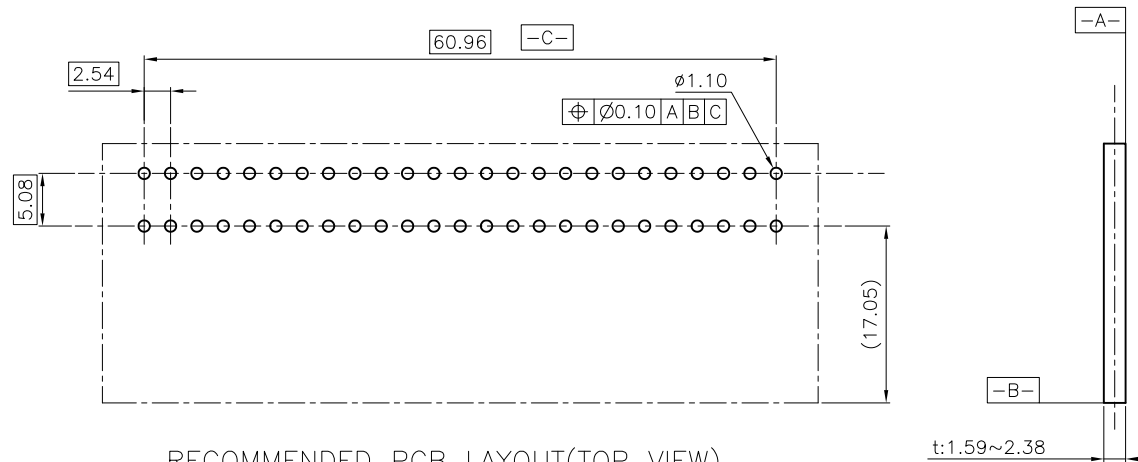
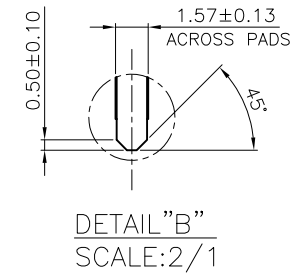
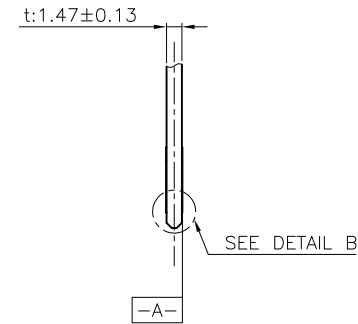
- 1. HOUSING MATERIAL: HIGH-TEMP THERMOPLASTIC, UL 94 V-0; COLOR: BLACK
- CONTACT MATERIAL: HIGH PERFORMANCE COPPER ALLOY
- 2. PLATING OPTION:
30u" Au ON CONTACT AREA, 100u" Sn ON SOLDER AREA BOTH OVER 50u" Ni UNDERPLATED.
- 3. PACKAGED IN TRAYS.



							TOLERANCES UNLESS OTHERWISE SPECIFIED	TITLE HIGH POWER CARD EDGE, R/A 50 PIN DIP TYPE					UNIT mm
							X. ±0.50 X.X ±0.30 X.XX ±0.20 X.XXX ±0.15 ANGEL ±3°	ORIGINAL DATA 07-28'14					
							MATERIAL SEE NOTES	DWN. Grace_Yu					PART NO.
B	ADD P./N.	N1605199	Grace			05-09'16	FINISH SEE NOTES	CHK. _____	DWG. NO. C-H2-006			SHEET 1 of 3	
A	Released	--	Grace	--	Mark	07-28'14		APVD. Mark_Chen					
REV.	DESCRIPTION	ECN NO.	DWN.	CHK.	APVD.	DATE							

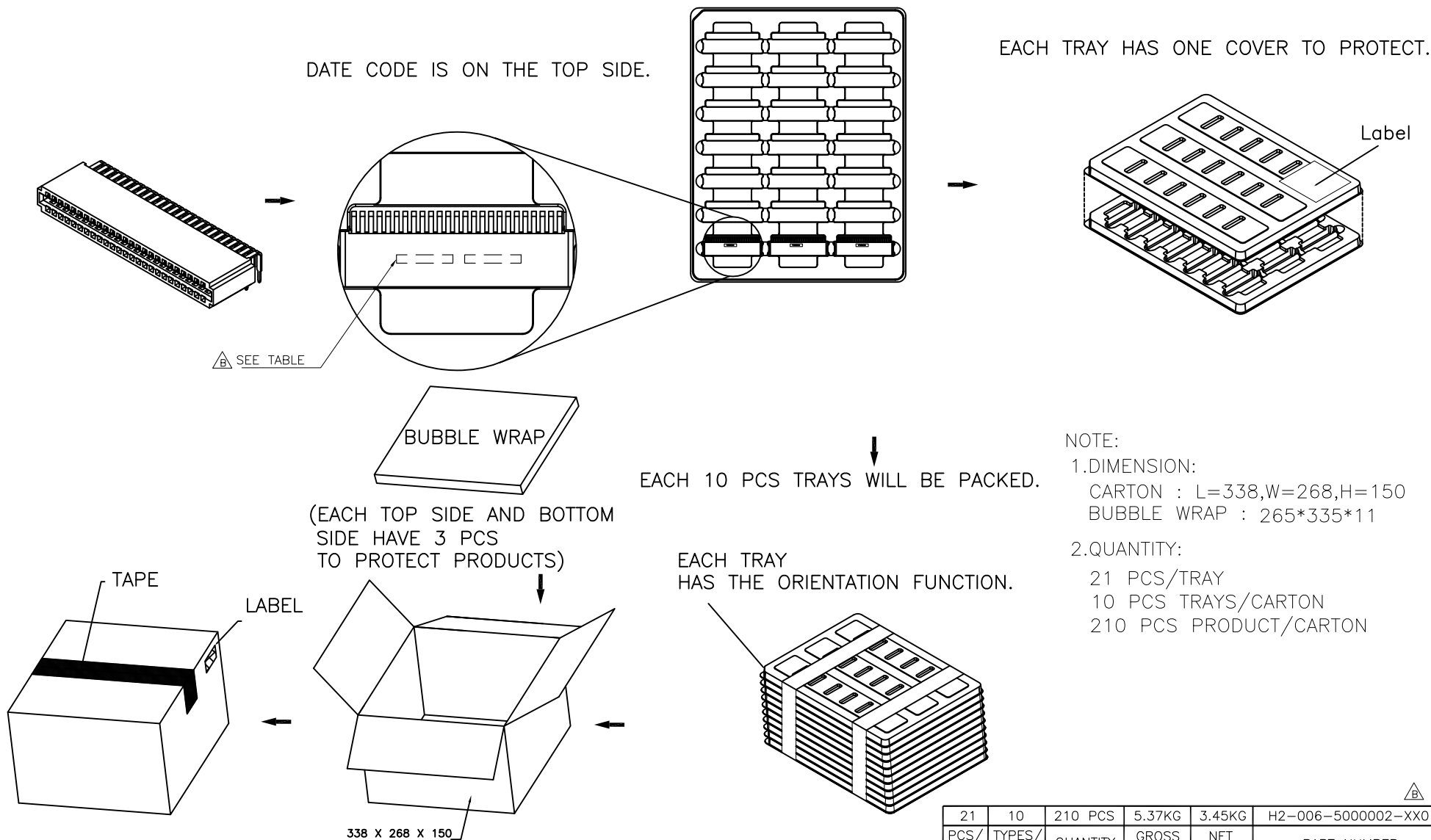


RECOMMENDED EDGE CARD LAYOUT
(TOLERANCE ± 0.05)



RECOMMENDED PCB LAYOUT(TOP VIEW)
TOLERANCE ± 0.05

							TOLERANCES UNLESS OTHERWISE SPECIFIED	TITLE	UNIT
							X. ±0.50	HIGH POWER CARD EDGE, R/A 50 PIN DIP TYPE	mm
							X.X ±0.30	ORIGINAL DATA	
							X.XX ±0.20	07-28'14	
							X.XXX ±0.15	DWN. Grace_Yu	
							ANGEL ±3°	CHK. _____	
B	ADD P./N.	N1605199	Grace			05-09'16	MATERIAL	PART NO.	SCALE
A	Released	--	Grace	--	Mark	07-28'14	SEE NOTES	SEE TABLE	1:1
REV.	DESCRIPTION	ECN NO.	DWN.	CHK.	APVD.	DATE	FINISH	DWG. NO.	SHEET
							SEE NOTES	APVD. Mark_Chen	2 OF 3



21	10	210 PCS	5.37KG	3.45KG	H2-006-5000002-XX01X
PCS/ TRAY	TYPES/ BOX	QUANTITY	GROSS WEIGHT	NET WEIGHT	PART NUMBER

						TOLERANCES UNLESS OTHERWISE SPECIFIED		TITLE		UNIT
						X. ±0.50		HIGH POWER CARD EDGE, R/A 50 PIN DIP TYPE		mm
						X.X ±0.30		ORIGINAL DATA		
						X.XX ±0.20		07-28'14		
						X.XXX ±0.15		DWN. Grace_Yu		
						ANGEL ±3°		CHK. _____		
						MATERIAL SEE NOTES		PART NO. SEE TABLE		
						FINISH SEE NOTES		DWG. NO. C-H2-006		
								APVD. Mark_Chen		
								SCALE 1:1		
								SIZE A3		
								REV. B		
								SHEET 3 OF 3		